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19009-0285 (US). **DELEY, Michael** [US/US]; 2021 Mulberry Lane, Warrington, PA 18976 (US).

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(74) Agent: **SPLETZER, Christopher M., Sr.**; Kulicke and Soffa Industries, Inc., 1005 Virginia Drive, Fort Washington, PA 19034 (US).

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(71) Applicant (for all designated States except US):
KULICKE AND SOFFA INDUSTRIES, INC. [US/US]; 1005 Virginia Drive, Fort Washington, PA 19034 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **COUEY, Jeremiah** [US/US]; 8011 Cooke Road, Elkins Park, PA 19027 (US). **SARBACKER, Shawn** [US/US]; 107 Tennyson Lane, North Wales, PA 19454 (US). **ODHNER, Matthew** [US/US]; 2626 Alden Rd., Bryn Athyn, PA

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(54) Title: METHODS OF TEACHING BONDING LOCATIONS AND INSPECTING WIRE LOOPS ON A WIRE BONDING MACHINE, AND APPARATUSES FOR PERFORMING THE SAME

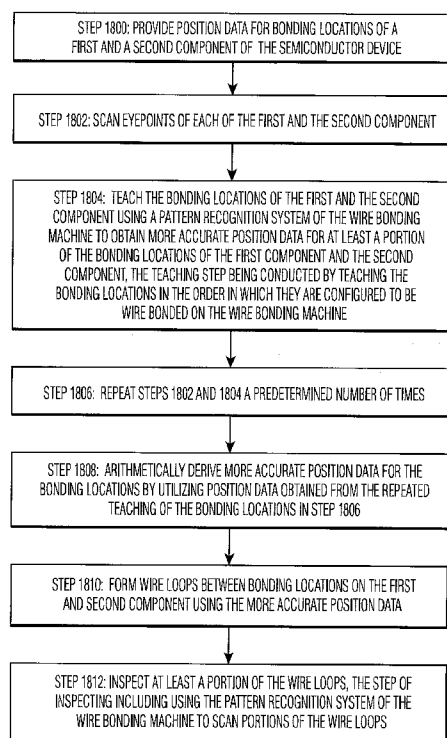


FIG. 18

(57) Abstract: A method of teaching bonding locations of a semiconductor device on a wire bonding machine is provided. The method includes (1) providing the wire bonding machine with position data for (a) bonding locations of a first component of the semiconductor device, and (b) bonding locations of a second component of the semiconductor device; and (2) teaching the bonding locations of the first component of the semiconductor device and the second component of the semiconductor device using a pattern recognition system of the wire bonding machine to obtain more accurate position data for at least a portion of the bonding locations of the first component and the second component. The teaching step is conducted by teaching the bonding locations in the order in which they are configured to be wire bonded on the wire bonding machine.



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